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(54) Title: COATING COMPOSITIONS FOR SOLDER SPHERES, POWDERS AND PREFORMS, METHODS OF PRODUCTION AND USES THEREOF

(57) Abstract: A solder material has been produced and is described herein that comprises a conventional solder component, such as a solder sphere, solder ball, solder powder, solder preform, some other suitable material or form of solder or a combination thereof and a coating composition. Solder parts and/or solder materials described herein may be produced by a) providing a solder component, b) providing a coating precursor material, c) providing a solvent, d) blending the coating precursor material and the solvent, such that the coating precursor material is substantially solvated, to form a coating composition, and e) applying or coupling the coating composition to the solder component.



WO 2004/047507 A2